

S E R V I C E N O T E

SUPERSEDES: NONE

54659B Module**Serial Numbers:** US00000000/ US35460649**Potential short between PC board and module cover.****Duplicate Service Notes:** 54652B-02**To Be Performed By:** Agilent-Qualified Personnel Only**Parts Required:** P/N 0460-1282**Situation:**

The tabs on which the PC board rests are conductive and two of these tabs touch vias on the PC board. These vias are normally covered with an insulating material on the PC board but the layer is very thin and does not always cover the vias. The two potential vias which can short are connected to address lines 14 and 16 on the module interface. When the address lines are shorted to ground, the oscilloscope has a drastic failure; the microprocessor may corrupt the system and module Non-Volatile RAM data causing erratic displays, lock-ups and lost calibration factors.

Continued

DATE: January 1997

ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION:			
MODIFICATION RECOMMENDED			
ACTION CATEGORY:	<input type="checkbox"/> IMMEDIATELY <input type="checkbox"/> ON SPECIFIED FAILURE <input checked="" type="checkbox"/> AGREEABLE TIME	STANDARDS: LABOR 0.5 Hours	
LOCATION CATEGORY:	<input type="checkbox"/> CUSTOMER INSTALLABLE <input type="checkbox"/> ON-SITE <input checked="" type="checkbox"/> SERVICE CENTER	SERVICE INVENTORY: <input type="checkbox"/> RETURN <input type="checkbox"/> SCRAP <input checked="" type="checkbox"/> SEE TEXT	USED PARTS: <input type="checkbox"/> RETURN <input type="checkbox"/> SCRAP <input checked="" type="checkbox"/> SEE TEXT
AVAILABILITY:	PRODUCT'S SUPPORT LIFE		AGILENT RESPONSIBLE UNTIL: January 1998
AUTHOR: TG	ENTITY: 0840	ADDITIONAL INFORMATION:	

Solution/Action:

Upgrade Instructions for 54659B Interface Module

The following steps are required to repair the Interface Module:

STEP 1: Remove the board from the module

- a. Place module on hard surface with large connector facing up. With small screw driver, press four latches "A" (figure 1) toward center of the module and downward, while pulling module apart.
- b. Pull module apart with slight pressure as latches are being released.
- c. Press smaller latch "B" (figure 1) in raised portion of module and pull module apart.
- d. Remove board from module.

CAUTION

While putting tape on the board, proper ESD care must be taken to prevent any static discharge that may damage components.

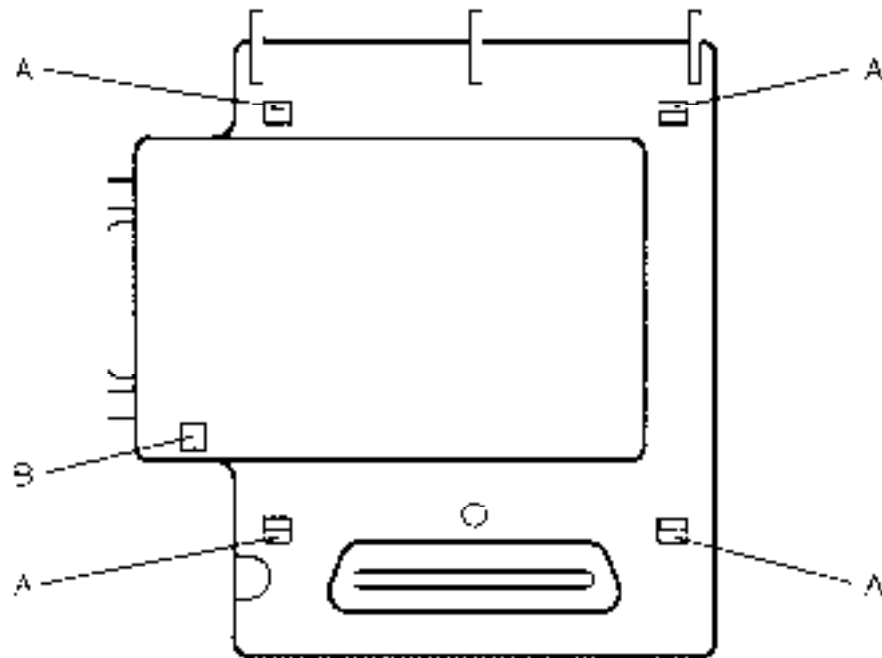
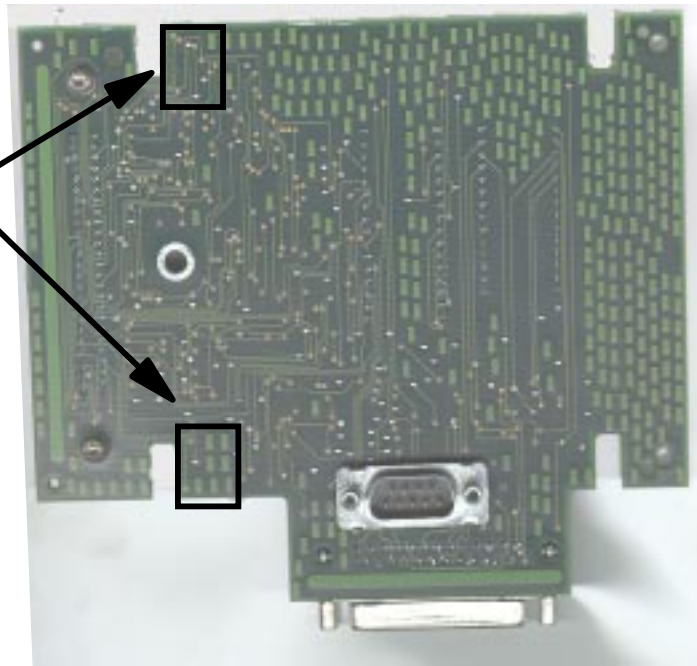


Figure 1

STEP 2: Install insulating tape on the module PC board.

- a. Cut two pieces of tape from roll, each piece one inch in length.
- b. Begin on the back side of board, place 1/2 inch of tape on the back side of the board. (See Figure 2) Wrap around the edge and place the other 1/2 inch of the tape on the top side of the board. (See Figure 3) This process is necessary because the vias are located on both sides of the board.

Figure 2:
Cover these two
areas of board
with tape, wrapping
around edge
of board to the
front .



STEP 3: Reinstall the board into the module

- a. Place the board back into the module case making sure the spring contacts are on the outside of the connector housing and that the flange of the smaller connector is properly seated in the slot.
- b. Insure that the four holes in the corners of the board are seated properly on the locating pins.
- c. Place the rear cover on the module and press until all latches are engaged.

Module is now ready for use and may be reinstalled on the instrument.

Figure 3:
Wrap the tape from the back of the board around to the front of the board, covering the traces.

